

WEST Search History

DATE: Tuesday, April 23, 2002

<u>Set Name</u>	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u>
side by side			result set
<i>DB=USPT,PGPB,JPAB,EPAB,DWPI,TDBD; PLUR=YES; OP=OR</i>			
L17	sacrific\$4 with (solder adj mask)	7	L17
<i>DB=USPT; PLUR=YES; OP=OR</i>			
L16	L15	3	L16
L15	(solder with opening\$1 with BPSG)	3	L15
L14	L3 and CMP	113	L14
L13	(CMP with (contact or land\$3)) and solder	5	L13
L12	4367119.pn.	1	L12
<i>DB=USPT,PGPB,JPAB,EPAB,DWPI,TDBD; PLUR=YES; OP=OR</i>			
L11	solder with coat\$3 with tungsten	54	L11
L10	solder with tungsten with (protrud\$3 or protrusion)	2	L10
L9	L8 and (solder adj mask)	15	L9
L8	(tungsten with solder) and (contact or bump)	405	L8
L7	(tungsten with solder with mask\$3)	1	L7
L6	(tungsten with plug with solder with mask\$3)	0	L6
<i>DB=USPT; PLUR=YES; OP=OR</i>			
L5	5550427.pn. and solder	0	L5
L4	L3 and (solder with mask\$3)	201	L4
L3	((438/597 438/612 438/613 438/614 438/615 438/616 438/617)!.CCLS.)	1311	L3
<i>DB=PGPB,JPAB,EPAB,DWPI,TDBD; PLUR=YES; OP=OR</i>			
L2	semiconductor and (etch\$3 with oxide) and protrud\$3 and bump\$3	23	L2
<i>DB=USPT; PLUR=YES; OP=OR</i>			
L1	semiconductor and (etch\$3 with oxide) and protrud\$3 and bump\$3	139	L1

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L18	(shape with bump with (aperture\$1 or opening\$1))	210	L18
L17	sacrific\$4 with (solder adj mask)	7	L17
<i>DB=USPT; PLUR=YES; OP=OR</i>			
L16	L15	3	L16
L15	(solder with opening\$1 with BPSG)	3	L15
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L13	(CMP with (contact or land\$3)) and solder	5	L13
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L16 L15 3 L16

L15 (solder with opening\$1 with BPSG) 3 L15

L14 L3 and CMP 113 L14

L13 (CMP with (contact or land\$3)) and solder 5 L13

L12 4367119.pn. 1 L12

DB=USPT,PGPB,JPAB,EPAB,DWPI,TDBD; PLUR=YES; OP=OR

L11 solder with coat\$3 with tungsten 54 L11

L10 solder with tungsten with (protrud\$3 or protrusion) 2 L10

L9 L8 and (solder adj mask) 15 L9

L8 (tungsten with solder) and (contact or bump) 405 L8

L7 (tungsten with solder with mask\$3) 1 L7

L6 (tungsten with plug with solder with mask\$3) 0 L6

DB=USPT; PLUR=YES; OP=OR

L5 5550427.pn. and solder 0 L5

L4 L3 and (solder with mask\$3) 201 L4

L3 ((438/597 |438/612 |438/613 |438/614 |438/615 |438/616 |438/617)!.CCLS.) 1311 L3

DB=PGPB,JPAB,EPAB,DWPI,TDBD; PLUR=YES; OP=OR

L2 semiconductor and (etch\$3 with oxide) and protrud\$3 and bump\$3 23 L2

DB=USPT; PLUR=YES; OP=OR

L1 semiconductor and (etch\$3 with oxide) and protrud\$3 and bump\$3 139 L1

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L3	((438/597 438/612 438/613 438/614 438/615 438/616 438/617)!.CCLS.)	1311	L3

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L2	semiconductor and (etch\$3 with oxide) and protrud\$3 and bump\$3	23	L2
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